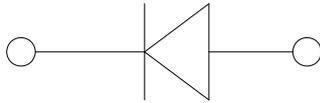
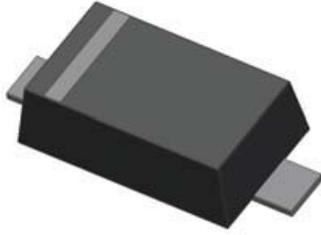


Schottky Barrier Diode



Features

- V_R 30V
- I_F 200mA

Typical Applications

- Low Forward Voltage Drop

Mechanical Data

- **Package:** SOD-523
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end
- **Marking:** B

■ Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	Limit Max
Power Dissipation	P_D	mW		150
Storage Temperature	T_{STG}	°C		-40 to +125
Junction Temperature	T_J	°C		125
DC Reverse Voltage	V_R	V		30
Average Rectified Forward Current	I_{FAV}	mA		200
Non-repetitive Peak Forward Surge Current	I_{FSM}	A	8.3ms single half sine-wave	1.0

■ Electrical Characteristics ($T_a=25^\circ\text{C}$ Unless otherwise specified)

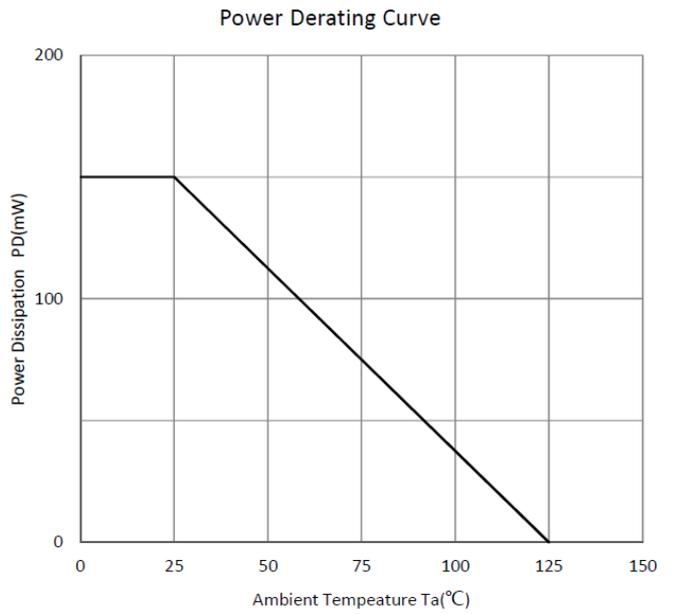
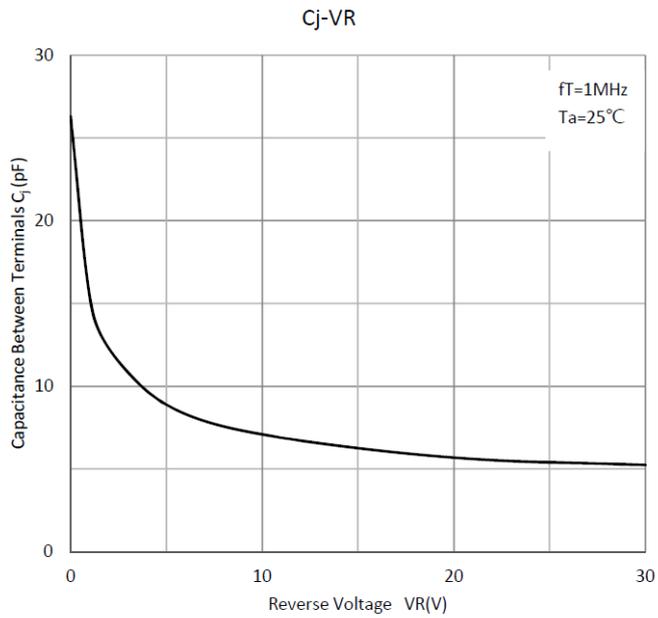
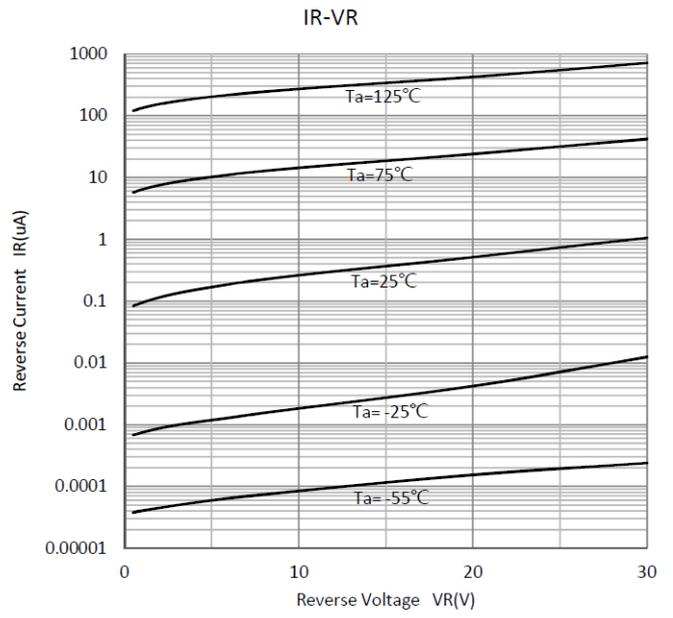
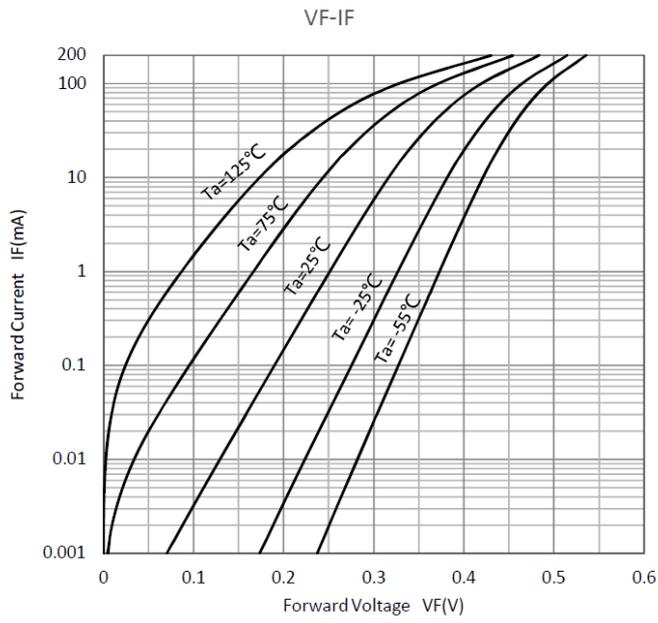
Item	Symbol	Unit	Conditions	Min	Max
Breakdown Voltage	V_R	V	$I_R=500\mu\text{A}$	30	
Forward Voltage	V_F	V	$I_F=200\text{mA}$		0.6
Reverse Leakage Current	I_R	μA	$V_R=10\text{V}$		1

■ Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
RB520S-30	F2	Approximate 0.0025	8000	80000	320000	7" reel

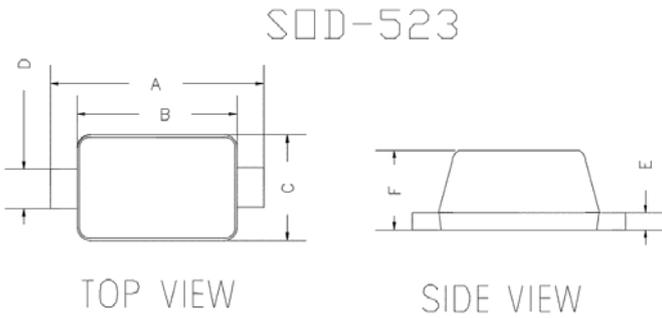


■ Characteristics(Typical)





■ Outline Dimensions

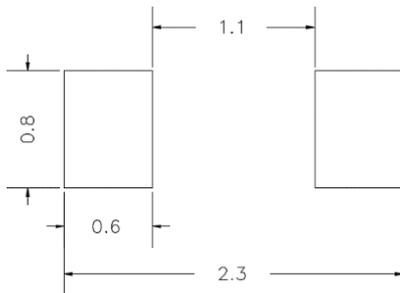


DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	0.059	0.067	1.500	1.700
B	0.043	0.051	1.100	1.300
C	0.028	0.035	0.700	0.900
D	0.010	0.014	0.250	0.350
E	0.002	0.008	0.050	0.200
F	0.020	0.028	0.500	0.700

Note:

- All dimensions are in millimeters (mm) unless otherwise specified.
[所有尺寸均以毫米为单位, 除非另有说明]
- General tolerances: $\pm 0.10\text{mm}$ unless otherwise specified.
[通用公差为 $\pm 0.10\text{mm}$, 除非另有说明]
- Dimensions and tolerances per ASME Y14.5M-2018.
[尺寸和公差遵循 ASME Y14.5M-2018 标准]
- All dimensions shown are exclusive of burrs and gate residues.
Burr and gate vestiges shall not exceed 0.15 mm in maximum.
[所有尺寸均不包括毛刺和浇口残留。毛刺与浇口残留的尺寸最大不得超过 0.15mm]
- Dimension b does not include dambar protrusion of max 0.100 mm per side.
[尺寸b不包括单边最大0.100 MM的中筋凸出部分]
- Dimensions B and C are the overall extreme outer dimensions of the mold compound. These dimensions exclude mold flash, lead flash, protrusions and burrs but include the maximum allowable mold mismatch.
[B和C是塑封体的外部极限尺寸, 不包括包封溢料、内引线溢料、凸出部分以及胶体毛刺, 但是包含了包封错位的最大尺寸]
- Formed leads shall be planar with respect to one another within a maximum of 0.076 mm relative to the seating plane.
[成型的管脚应为同一平面, 共面性最大为0.1mm]

■ Soldering Footprint



UNIT: mm

SUGGESTED SOLDER PAD LAYOUT



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